



SLOVENSKI STANDARD

SIST EN 60749-3:2017

01-september-2017

Nadomešča:
SIST EN 60749-3:2004

Polprevodniški elementi - Mehanske in klimatske preskusne metode - 3. del: Zunanji vizualni pregled (IEC 60749-3:2017)

Semiconductor devices - Mechanical and climatic test methods - Part 3: External visual examination (IEC 60749-3:2017)

Halbleiterbauelemente - Mechanische und klimatische Prüfverfahren - Teil 3: Äußere Sichtprüfung (IEC 60749-3:2017)

Dispositifs à semiconducteurs - Méthodes d'essais mécaniques et climatiques - Partie 3: Examen visuel externe (IEC 60749-3:2017)

Ta slovenski standard je istoveten z: **EN 60749-3:2017**

ICS:

31.080.01	Polprevodniški elementi (naprave) na splošno	Semiconductor devices in general
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EUROPEAN STANDARD

EN 60749-3

NORME EUROPÉENNE

EUROPÄISCHE NORM

June 2017

ICS 31.080.01

Supersedes EN 60749-3:2002

English Version

**Semiconductor devices - Mechanical and climatic test methods -
Part 3: External visual examination
(IEC 60749-3:2017)**

Dispositifs à semiconducteurs - Méthodes d'essais
mécaniques et climatiques - Partie 3: Examen visuel
externe
(IEC 60749-3:2017)

Halbleiterbauelemente - Mechanische und klimatische
Prüfverfahren - Teil 3: Äußere Sichtprüfung
(IEC 60749-3:2017)

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European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

CEN-CENELEC Management Centre: Avenue Marnix 17, B-1000 Brussels

EN 60749-3:2017**European foreword**

The text of document 47/2345/FDIS, future edition 2 of IEC 60749-3, prepared by IEC/TC 47 "Semiconductor devices" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN 60749-3:2017.

The following dates are fixed:

- latest date by which the document has to be implemented at national level by publication of an identical national standard or by endorsement (dop) 2018-01-07
- latest date by which the national standards conflicting with the document have to be withdrawn (dow) 2020-04-07

This document supersedes EN 60749-3:2002.

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In the official version, for Bibliography, the following note has to be added for the standard indicated :

IEC 60749-9	NOTE	Harmonized as EN 60749-9.
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Annex ZA (normative)

Normative references to international publications with their corresponding European publications

The following documents, in whole or in part, are normatively referenced in this document and are indispensable for its application. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE 1 When an International Publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

NOTE 2 Up-to-date information on the latest versions of the European Standards listed in this annex is available here: www.cenelec.eu.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 61340-5-1	-	Electrostatics - Part 5-1: Protection of electronic devices from electrostatic phenomena - General requirements	EN 61340-5-1	-
IEC 62483	-	Environmental acceptance requirements for tin whisker susceptibility of tin and tin alloy surface finishes on semiconductor devices	-	-

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INTERNATIONAL STANDARD

**Semiconductor devices – Mechanical and climatic test methods –
Part 3: External visual examination**

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

**SEMICONDUCTOR DEVICES –
MECHANICAL AND CLIMATIC TEST METHODS –****Part 3: External visual examination**

FOREWORD

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International Standard IEC 60749-3 has been prepared by IEC technical committee 47: Semiconductor devices.

This second edition cancels and replaces the first edition published in 2002. This edition constitutes a technical revision.

This edition includes the following significant technical changes with respect to the previous edition:

- a) reference to the need for ESD protection;
- b) inclusion of information on the phenomenon of tin whiskers;
- c) inclusion of an optional report form/checklist.